

Title (en)  
METHOD FOR THE MANUFACTURE OF AN ELECTRONIC ASSEMBLY

Title (de)  
VERFAHREN ZUR HERSTELLUNG EINER ELEKTRONISCHEN BAUGRUPPE

Title (fr)  
PROCÉDÉ DE FABRICATION D'UN MODULE ÉLECTRONIQUE

Publication  
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Application  
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Abstract (en)  
[origin: WO2009153129A2] The invention relates to a method for the manufacture of an electronic assembly, comprising at least one electronic component (9) and also a conductor track structure (7) which is used to make contact with the at least one electronic component (9). The method involves a first step being used to pattern a conductive foil (1) to produce the conductor track structure (7). In a second step, the conductor track structure (7) has the at least one electronic component (9) fitted. In a final step, a further foil is laminated onto the conductive foil (1) fitted with the at least one electronic component (9) on the side on which the conductive foil (1) has the at least one electronic component (9) fitted.

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Citation (search report)  
See references of WO 2009153129A2

Citation (examination)  
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• US 2005006142 A1 20050113 - ISHIMARU YUKIHIRO [JP], et al  
• US 2003137045 A1 20030724 - SUGAYA YASUHIRO [JP], et al  
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